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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	317000
Number of Logic Elements/Cells	840000
Total RAM Bits	53248000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma9k1h40c2n

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Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimu f h	Typical	Maximun ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Possiver analog newer supply (right side) GX, GS	0.87	0.90	0.93	V
(2)	Receiver analog power supply (right side) GA, G3	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL} (2)	Transmitter analog power supply (left sid	e) GX, GS	0.87	0.90	0.93	V
	Transmitter analog power supply (left sid	e) GA, G3	0.97	1.0	1.03	v
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V _{CCT_GXBR}	Transmitter analog newer supply (right ai	4°/ C^ C	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right si	de) GX, GS	0.97	1.0	1.03	
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V _{CCL_GTBR}	Transmitter clock network persupply	GT	1.02	1.05	1.08	٧
V _{CCH_GXBL}	Transmitter output buffer power supply (liside)	eft _G X, GS, G1	1.425	1.5	1.575	
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	

Notes to Table 7.

⁽¹⁾ This supply must be connected to 3.0th/efCMU PLL, receiver CDR, or both, arrifigured at a base data rate > 6.5 Gbpstol&p5 Gbps, you can connect this supply either 3.0 V or 2.5 V.

⁽²⁾ Refer to Table & select the correct powsupply level for your design.

⁽³⁾ When using ATX PLLs, the supply must be 3.0 V.

⁽⁴⁾ This value describes the budget for the (SDECic) power supply tolerance and dioes include the dynaic tolerance requirements. Refer to the PDN tool for the additial budget for the dynamic tolerance requirements.

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I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin le akage current specifications.

Table 9. I/O Pin Leakage Current for Stratix V Devídes

Symbol	Description	Conditions	Min	Тур	Max	U	nit
I	Input pin	$V = 0 V \text{ to } V_{CIOMAX}$	-30	_	30	μΑ	•
I _{OZ}	Tri-stated I/O pin	∂= 0 V to V _{CIOMAX}	-30		30	μA	

Note to Table 9

(1) If $V_O = V_{CCIO}$ to $V_{CCIOMax}$ 100 μA of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

		_		_			Vo	CCIO	_				
Parameter	Symbo	I Conditions	3 1.2	2 V	1.	5 V	1.	.8 V	2	.5 V	3	.0 V	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Ма	x
Low sustaining current	I _{SUSL}	$V_{IN} > V_{L}$ (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0		μA
High sustaining current	I _{SUSH}	V _{IN} < V _H (minimum)	-22.5	_	-25.0	_	-30.0) —	– 50.	0 —	-70	0 –	- μ
Low overdrive current	I _{ODL}	0V < V _N < V _{CCIO}		120	_	160		200	_	300	_	500	μΑ
High overdrive current	I _{ODH}	0V < 1/N < VCCIO		-120		-160		-200		-300) —	– 50	10 μ/
Bus-hold trip point	V_{TRIP}	_	0.45	0.95	0.50	1.00	0.68	3 1.0	7 0.7	0 1.	70 0.8	30 2	.00

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Device(Part 1 of 2)

Symbol	Description		Calibration Accuracy					
		Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit	
25-: R _S	Internal series termination with calibration (25: setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%	

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)

Symbol	Description	9c1Q(A)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
		1.5	0.273	
		1.2	0.317	

Note to Table 13

(1) Valid for a $\mbox{\em V_{CIO}}$ range of ±5% and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
G _{OTB}	Input capacitance on the top and bottom I/O pins	6	рF
G _{OLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback p	ins	6 p

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	30 79 A
I _{IOPIN (AC)}	AC current per I/O pin	8 mA
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 kg/s= 10 dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devides

Symbol	Description	V _{CCIO} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	k
		2.5 ±5%		
	Value of the I/O pin pull-up resistor before	9 1.8 ±5%	25	k
R_{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	k
	pull-up resistor option.	1.35 ±5%	25	k
		1.25 ±5%	25	k
		1.2 ±5%	25	k

Notes to Table 16

- (1) All I/O pins have an or opti to enable the weak pull-repristor except the configuration, test, and JTAG pins.
- (2) The internal/weak pull-down feature is **pra**lvailable for the JTATGK pin. The typical vall**ier** this internal weak pull-down resistor is approximately 25 k
- (3) The pin pull-up resistance vestumay be lower if an extersalurce drives the pin higher that the pin higher than the pin hig
- (4) These specifications are distavith a ±10% tolerance cover changes over PVT.

I/O Standard Specifications

Table 17through Table 22list the input voltage (V $_{IH}$ and V $_{IL}$), output voltage (V $_{OH}$ and V $_{OL}$), and current drive characteristics (I $_{OH}$ and I $_{OL}$) for various I/O standards supported by Stratix V devices. These tablesalso show the Stratix V device family I/O standard specifications. The V $_{OL}$ and V $_{OH}$ values are valid at the corresponding I $_{OH}$ and I $_{OL}$, respectively.

For an explanation of the terms used in Table 17through Table 22, refer to "Glossary" on page 65 For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486

Table 17. Single-Ended I/O Standards for Stratix V Devices

I/O		V _{CCIQ} (V)		Y _L (V)		V ⊢	_I (V)	Pr(A)	ŊH(Λ)	I _{OL}	I _{OH}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mA)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	2 -2
LVCMOS	2.85	3	3.15	-0.3	3 0.8	1.7	3.6	0.2	. _{CCI} √ 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	,	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} - 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2

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Table 23. Transceiver Specifications for Stratix V GX and GS De∜ice®art 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	er Speed e 1	Trai	nsceive Grad	er Speed e 2	Trar	nsceive Grad	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Mir	ту	р Мах	
	DC Gain Setting = 0	_	0	_		0	_	_	0	_	dB
	DC Gain Setting = 1	_	2			2			2		dB
Programmable DC gain	DC Gain Setting = 2	_	4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_		6	_	_	6	_	dB
	DC Gain Setting = 4		8	_		8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_				1	.4-V a	nd 1.5-V F	PCML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	60	0 –	8500/ - 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	60	0 –	8500/ - 10312.5 (24)	Mbps
	85-: setting	_	85 ± 20%	_	_	85 ± 20%	_		85 ± 20%	_	:
Differential on-	100-: setting	_	100 ± 20%	1		100 ± 20%	-		100 ± 20%	1	:
chip termination resistors	120-: setting	_	120 ± 20%	_		120 ± 20%	_		120 ± 20%	_	:
	150-: setting	_	150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	:
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_	_	650	_	_	650	_	_	650	_	mV
Rise time ⁽⁷⁾	20% to 80%	30		160	30		160	30	_	- 160	ps
Fall time ⁽⁷⁾	80% to 20%	30		160	30		160	30		- 160	ps
Intra-differential pair skew	Tx V _{cM} = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120		_	120	_	_	120	ps

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Table 23. Transceiver Specifications for Stratix V GX and GS Device (Part 7 of 7)

Symbol/ Description	Conditions	Tra	nsceive Grad	er Speed e 1	Trai	nsceive Grad	er Speed e 2	Trar	nsceive Grad	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Mir	Ту	р Мах	
t _{pll_lock} ⁽¹⁶⁾	_	_	_	10	_	_	10	_	_	10	μs

Notes to Table 23

- (1) Speed grades shown Tiable 23 efer to the PMA Speed Grade in the description of the maximum destination could be restricted by the Core/PCS speed grade. Control of the maximum data rate spicociations in each speed grade communities offered. For more information about device ordering codes, refer to the maximum data rate spicociations in each speed grade communities.
- (2) The reference clock commonded oltage is equal to the of GXP ower supply level.
- (3) This supply must be connected to 1.0th/eiftransceiver is configured a data rate > 6.5 Gbpasnd to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates@bps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged ration at this bsolute maximum.
- (6) The differential eye opening specificattothe receiver inpropriate assumes that eceiver Equalizations disabled. If you enabled ever Equalization, the receiver circuitry can tolerate a lower minimum opening, depending three equalization level.
- (7) The Quartus II software autdireally selects the approxete slew rate depending on the configured data rate or functionally
- (8) The input reference clock freque options depend on the detailer and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The to that is the AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receiverCto lock to the input reference cloverquency after coming out of reset.
- (12) time required for the receiver CDRttot recovering valid data after the is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required fothe receiver CDR to start recoverialid data after thrx_is_lockedtodata signal goes high wher CIBR is functioning in the manual mode.
- (14) t_{LTR_LTD_manu} the time the receiver CDR must be included to reference (LTR) interpolated the rx_istockedtoref signal gets high when the CDR is functioning in the manual mode.
- (15) t_{oll powerdown} is the PLL powerdown minimum pulse width.
- (16) t_{bll_lock} is the time required for the transmit@MU/ATX PLL to lock to the ut reference clock frequerafter coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement fat Receivence clock frequenciative than 100 MHz, use the dowing formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to pedifferential input voltage bafter device configuration is equal to 4 x (absolute for receiver pin 10/1).
- (19) For ES devices_RPeis 2000: ±1%.
- (20) To calculate the REFCLK phase noise rement at frequencies other than 622 Misle, the following forma: REFCLK phase at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host internal Notation in the stratic very second of the strati
- (22) Refer toFigure 2
- (23) For oversampling designs topport data rates less than then imum specification, the CDReds to be in LTR mode only.
- (24) I3YY devices can achieve dates up to 10.3125 Gbps.
- (25) When you use fPLL asTXPLL of the transceiver.
- (26) REFCLKperformance requires to meet transmireFCLKphase noise specification.
- (27) Minimum eye opening of 85 mV isydor the unstressed input eye condition.

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date(Rafte

M = d = (2)	Transceiver	PMA Width	20	20	16	16	10	10) 8		8
Mode (2)	Speed Grade	PCS/Core Width	40	20	32	16	2	0 1	0	6	8
	1	C1, C2, C2L, I2, I2 core speed grade	L _{12.2}	11.4	9.76	9.12	6.5	5.8	3 5.	2 4	.72
	2	C1, C2, C2L, I2, I2 core speed grade	L _{12.2}	11.4	9.76	9.12	6.5	5.8	3 5.	2 4	.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.2	4 3	.76
FIFO		C1, C2, C2L, I2, I2 core speed grade	L 8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.	.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	3 4.	7 4.	24	3 76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.2	4 3	.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.8	4 3	3.44
	1	C1, C2, C2L, I2, I2 core speed grade	L _{12.2}	11.4	9.76	9.12	6.1	5.7	7 4.8	8 4	1.56
	2	C1, C2, C2L, I2, I2 core speed grade	L _{12.2}	11.4	9.76	9.12	6.1	5.7	7 4.8	8 4	1.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.9	6 3	3.6
Register		C1, C2, C2L, I2, I2 core speed grade	L 10.3125	10.3125	10.312	5 10.312	25 6.	.1 5	.7 4	.88	4.50
3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	9 4.	5 3.	96	3.6	
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.9	6 3	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.5	2 3	5.28

Notes to Table 25

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can beguccerdiin FIFO mode or register modetherFIFO mode, the pointers are not fixed the latency can vary. In the register mode their mode the register mode the register mode the register mode to the register mode the register mode to the register mode the register mode to the register mode

⁽³⁾ The maximum data rateals o constrained by the transier speed grade. Referitable 1 for the transcerer speed grade.

Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

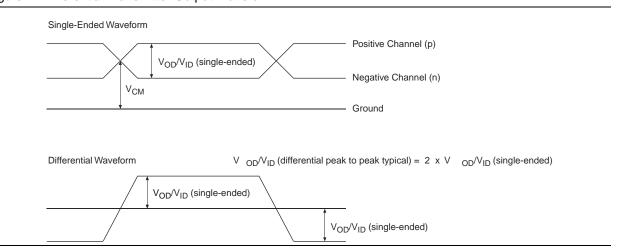


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)

Table 28 lists the Stratix V GT transceiver specifications.

Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 6 f 5)

Symbol/	Conditions		Transceive Speed Grad			Fransceive peed Grad		Unit			
Description		Min	Тур	Max	Min	Тур	Max				
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, V2PCML, Differential LVPECL, L and HCSL									
Otandards	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2/.5PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	1	40	_	710	40	_	710	MHz			
Input Reference Clock Frequency (ATX PL©)		100	_	710	100	_	710	MHz			
Rise time	20% to 80%	_	_	400	_	_	400				
Fall time	80% to 20%	-	_	400	_	_	400	ps			
Duty cycle	_	45	_	55	45	_	55	%			
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz			
Spread-spectrum downspread	PCle	_	0 to -0.5	_		0 to -0.	5 —	%			
On-chip termination resistors ⁽¹⁹⁾	_	_	100			100	_	:			
Absolute M _{AX} ⁽³⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V			
	RX reference clock pin	· _	_	1.2		_	1.2				
Absolute M _{IN}	_	-0.4		_	-0.4	_	_	V			
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV			
V _{ICM} (AC coupled)			050/1000²	2)	mV						
	RX reference clock pin	1.	.0/0.9/0.85	22)	1.0	0/0.9/0.85	22)	V			
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV			

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)

Symbol/ Description	Conditions		Transceive peed Grad			ransceive beed Grad		Unit
Description		Min	Тур	Max	Min	Тур	Max	
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90	_	_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
Ţ	≥1 MHz	_	_	-120	_	_	-120	
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREÉ ¹⁷⁾	_	_	1800 ± 1%	_	_	1800 ± 1%	_	:
Transceiver Clocks	•							
fixedclk clock frequency	PCIe Receiver Detect		100 or 125		_	100 or 125	l	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	ı	125	100	_	125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCM	IL, 1.5-V PC	CML, 2.5-V	PCML, L	VPECL, ar	nd LVDS
Data rate (Standard PC\$)1)	GX channels	600		8500	600		8500) Mbps
Data rate (10G PCS ^{§1)}	GX channels	600		12,500	600		12,50	00 Mbps
Data rate	GT channels	19,60	0 —	28,0	50 19,6	- 00	–	780 Mbj
Absolute M _{AX} for a receiver pir (3)	GT channels	_	1	1.2	_	_	1.2	V
Absolute M _{IN} for a receiver pin	GT channels	-0.4			-0.4		l	V
Maximum peak-to-pea	kGT channels	_	_	1.6	_	_	1.6	V
differential input voltage 1/5 (diff p-p) before device configuration 1/20)	GX channels				(8)			
	GT channels							
Maximum peak-to-pea differential input voltage ⅓ (diff p-p) after device configuration 16, (20)	k V _{CCR_GT®} 1.05 V (V _{ICM} = 0.65 V)	_	_	2.2	_	_	2.2	V
	GX channels				(8)			
	0.7	200			200			\/
Minimum differential eye opening at receive	GT channels	200			200			mV

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 6) 5)

Symbol/ Description	Conditions		Transceive Speed Grad			Fransceive peed Grad		Unit
Description		Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (14)	_	_		10	_	_	10	μs

Notes to Table 28

- (1) Speed grades shown refer to PMA Speed Grade in the vice ordering code. The maximum date could be restricted by the ordering speed grade. Contaged ur Altera Sales Represeive for the maximum datate specifications in eacheed grade combination for more information about deviced ring codes, refer to the training of the provided restriction of the provided restricti
- (2) The reference clock common mode volitage ual to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged ration at this bsolute maximum.
- (4) The differential eye opening specification the receiver input pins assumes therefore equalization is disabled. If speakle receiver equalization, the receiver circuitan tolerate a lower minimum eye opening on the equalization level.
- (5) Refer to Figure for the GT channel AC gain curves. The total weef Act gain is the Again minus the DC gain.
- (6) Refer to Figure for the GT channel DC gain curves.
- (7) CFP2 optical modules require host interface to have the receiver plants differentially terminated with 100The internal OCT feature is available after the Stratix V FPGA configuration is completed befores enting the optical module. Otherise, minimize unnecessary removal insertion with unconfigured devices.
- (8) Specifications for this parameter arestates as for Stratix V GX and GS devices Table 23 or specifications.
- (9) t_{LTR} is the time required for the receiverCto lock to the input reference clirequency after coming out of reset.
- (10) t_{LTD}is time required for the receiver CDRttart recovering valid data after the lockedtodata signal goes high.
- (11) t_{LTD_manual}s the time required foline receiver CDR to start receing valid data after the is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manu}s the time the receiver CDR must be ikelpick to reference (LTR) mode after this_lockedtoref signal goes high when the CDR is functioning the manual mode.
- (13) tpll_powerdown is the PLL powerdown minimum pulse width.
- (14) tpll_lock is the time required for the transmit@vIU/ATX PLL to lock to the time reference clock frequerativer coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement fat Receivence clock frequenciatiser than 100 MHz, use the dowing formula: REFCLK rms phase jitter at f(MHz) = REFROS phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to pedifferential input voltage bafter device configuration is equal to 4 x (absolute for receiver pin 15/1).
- (17) For ES devices, RREF is 20001%.
- (18) To calculate the REFCLK phase noise at frequencies other than 622 Milele, the following forula: REFCLK phase at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require Itost interface to have RD+ffedientially terminated with 100 The internal OCT feed is available after the Stratix V FPGA configuration completed. Altera recommends that FPGAgooonfion is completed before inserting the completed. Otherwise, minimize unnecessary removed linesertion with unconfigured devices.
- (20) Refer to Figure 4
- (21) For oversampling design to support dates less than the minimuspecification, the DR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL asTXPLL of the transceiver.

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

```
Interlaken
40G (XLAUI)/100G (CAUI)
10GBase-KR
QSGMII
XAUI
SFI
Gigabit Ethernet (Gbe / GIGE)
SPAUI
Serial Rapid IO (SRIO)
CPRI
OBSAI
Hyper Transport (HT)
SATA
SAS
```

CEI

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (-40° to 100°C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L sp grades)	eed ₅	_	800 ⁽¹⁾	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	d 5	_	800 ⁽¹⁾	MHz
	Input clock frequency (C4, I4 speed grades)	Ę	-	- ⁽¹ 650	MHz
f _{INPFD}	Input frequency to the PFD	5	_	325	MHz
f _{FINPFD}	Fractional Input clock frequency to the PFD		0 -	- 160	MH
	PLL VCO operating range (C1, C2, C2L, I2, I2L sprades)	eed 600	_	1600	MHz
f _{VCO} ⁽⁹⁾	PLL VCO operating range (C3, I3, I3L, I3YY spee grades)	d 600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	(00	— 130	00 MH
t _{EINDUTY}	Input clock or external feedback clock input duty of	ycle 4	4 0 -	- 60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 ⁽²⁾	MHz
f _{out}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580(2)	MHz
	Output frequency for an external clock output (C1 C2L, I2, I2L speed grades)	, C2 <u>,</u>	_	800(2)	MHz
f _{OUT_EXT}	Output frequency for an external clock output (C3 I3L speed grades)	, I3,	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4 speed grades)	, I4	_	553 ⁽²⁾	MHz
t _{OUTDUTY}	Duty cycle for a dedicated external clock output (v set to50%)	vhen ₄₅	50	55	%
t _{FCOMP}	External feedback clock compensation time	_		- 10	ns
f _{DYCONFIGCLK}	Dynamic Configuration Clock usednígmt_clk and scanclk	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertionageset	_	_	1	ms
t _{DLOCK}	Time required to lock dynamically (after switchove reconfiguring any non-post-scale counters/delays)		_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5	_	MHz
	PLL closed-loop high bandwidth		4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift			±50	ps
ARESET	Minimum pulse width on thateset signal	10	_	_	ns

Page 42 Switching Characteristics

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

Mode	C1	C2, C2l	₋ 12, 12l	. C3	13, I3L, I3YY	C4	14	Unit	
Modes using Three DSPs									
One complex 18 x 25	425	425	415	340	340	275	265	MHz	
Modes using Four DSPs									
One complex 27 x 27	465	465	465	380	380	300	290	MHz	

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devide(s) (Part 1 of 2)

		Resou	rces Used	ı			Perform	ance				
Memory	Mode	ALUTs	Memor	y C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit	
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	5 M	Hz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	5 M	Hz
IVILAD	Simple dual-port, x16 depth ⁽³⁾	0	1	675	675	533	400	675	533	400) M	Hz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450) M	Hz

Table 36. High-Speed I/O Specifications for Stratix V Devide(\$\mathbb{S}) (Part 2 of 4)

		C1			C2,	C2L,	12, 121	_ C	3, I3,	13L, 13Y	Υ	(C4,I4	11.7
Symbol	Conditions	Min	Тур	Max	Min	Тур) Max	с Mi	n Ty	үр Ма	x M	lin T	ур М	Unit ax
Transmitter														
	SERDES factor (= 3 to 10 ^{(9), (11),} (12), (13), (14), (15), (16)	J (6)	_	1600	(6)		1434	(6)	_	1250	(6)	_	1050	Mbps
	SERDES factor of t4	J												
True Differential I/O Standards	LVDS TX with DPA ⁽¹²⁾ , ⁽¹⁴⁾ , ⁽¹⁵⁾ , ⁽¹⁶⁾	(6)	_	1600	(6)	_	1600	(6)		1600	(6)	_	1250	Mbps
- f _{HSDR} (data rate)	SERDES factor (= 2, uses DDR Registers	J (6)	_	(7)	(6)		(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor . = 1, uses SDR Register	J (6)	_	(7)	(6)		(7)	(6)	_	(7)	(6)		(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor = 4 to 10 ⁽¹⁷⁾	J ₍₆₎	_	1100	(6)		1100	(6)	_	840	(6)	_	840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps		_	160			160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1			0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_		300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	—	_	0.2	_	_	0.2	_	_	0.2	—	_	0.25	UI

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	_	ns
t _{JPCO}	JTAG port clock to output		11)	ns
t _{JPZX}	JTAG port high impedance to valid output		· ⁽¹⁾ 14	ns
t _{JPXZ}	JTAG port valid output to high impedance		(1)14	ns

Notes to Table 46

- (1) A 1 ns adder is required for each woltage step down from 3.0 V. For example 12 ns if V_{CIO} the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock poetris 167 ns if VCCBAT is writthe range 1.2V-1.5V whyou perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size(﴿bit﴾)		
	ECCVA2	H35, F40, F3 5)	213,798,880	562,392		
	5SGXA3	H29, F3 ⁵ ³⁾	137,598,880	564,504		
	5SGXA4	_	213,798,880	563,672		
	5SGXA5	_	269,979,008	562,392		
	5SGXA7	_	269,979,008	562,392		
Stratix V GX	5SGXA9	_	342,742,976	700,888		
	5SGXAB	-	342,742,976	700,888		
	5SGXB5	_	270,528,640	584,344		
	5SGXB6	_	270,528,640	584,344		
	5SGXB9	_	342,742,976	700,888		
	5SGXBB	-	342,742,976	700,888		
Stratix V GT	5SGTC5	_	269,979,008	562,392		
Stratix V G I	5SGTC7	-	269,979,008	562,392		
	5SGSD3	_	137,598,880	564,504		
	ECCCD4	F1517	213,798,880	563,672		
Stratix V GS	5SGSD4	_	137,598,880	564,504		
Stratix v GS	5SGSD5	_	213,798,880	563,672		
	5SGSD6	_	293,441,888	565,528		
	5SGSD8	_	293,441,888	565,528		

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size({bit®)
Stratix V €¹)	5SEE9	_	342,742,976	700,888
Stratix V E	5SEEB	_	342,742,976	700,888

Notes to Table 47.

- (1) Stratix V E devices do not have PCI Expr@SSIe) hard IP. Stratix V E devices do sumpport the CvP oxiguration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSRbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting devi ce configuration options, refer to Configuration, Design Security, and RetecSystem Upgrades in Stratix V Devicesor creating configuration files, refer to the Quartus II Help.

Table 48 lists the minimum configuration ti me estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Seria(1)			Fast Passive Parallé ^{‡)}			
		Width	DCLK (MHz	Min Config Time (s)	Width	DCLK (MHz	Min Config Time (s)	
GX	А3	4	100	0.534	32	100	0.067	
		4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	B9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
GT	C5	4	100	0.675	32	100	0.084	
	C7	4	100	0.675	32	100	0.084	